3.5x3.5 mm SMD CHIP LED LAMP



ATTENTION

OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Part Number: AA3535QR4A25Z4S-W2

Warm White

Features

- White SMD package, silicone resin.
- Low thermal resistance.
- Compatible with IR-reflow processes.
- ESD protection.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 2a.
- RoHS compliant

Description

The source color devices are made with InGaN on Al₂O₃ substrate Light Emitting Diode.

Static electricity and surge damage the LEDS.

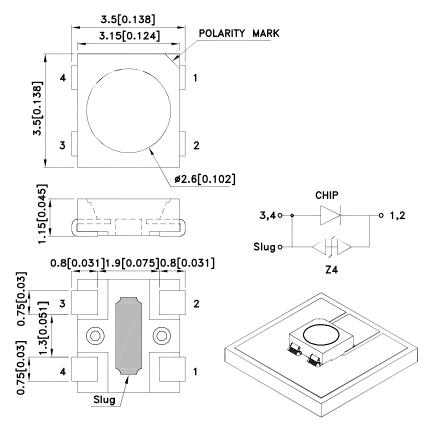
It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Applications

- Signal and symbol luminaire for orientation.
- Marker lights (e.g. steps, exit ways, etc).
- Decorative and entertainment lighting.
- · Commercial and residential lighting.
- Automotive interior lighting.

Package Dimensions



Notes

- All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
- 4. The device has a single mounting surface. The device must be mounted according to the specifications.





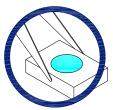
 SPEC NO: DSAM3339
 REV NO: V.3B
 DATE: FEB/02/2013
 PAGE: 1 OF 8

 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: Y.Liu
 ERP: 1201008033

Handling Precautions

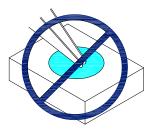
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

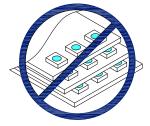


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

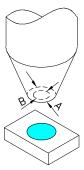




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

SPEC NO: DSAM3339 REV NO: V.3B DATE: FEB/02/2013 PAGE: 2 OF 8
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Y.Liu ERP: 1201008033

Selection Guide

Part No.	Color	CCT Range (K)			CRI	Lens Type	lv (cd) [2] @ 150mA		Фv (lm) [2] @ 150mA*		Viewing Angle [1]
		Min.	Тур.	Max.	Тур.		Min.	Тур.	Min.	Тур.	2 θ 1/2
AA3535QR4A25Z4S-W2	Warm White	2870	3000	3220	63	Water Clear	7	9	24	32	120°

Notes:

- θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 Luminous intensity/ luminous Flux: +/-15%.*LEDs are binned according to their luminous flux.
 Luminous intensity/ luminous Flux value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Symbol	Value	Unit
Power Dissipation	Po	600	mW
Junction Temperature [1]	TJ	110	°C
Operating Temperature	Тор	-40 To +85	°C
Storage Temperature	Tstg	-40 To +85	°C
DC Forward Current [1]	lF	150	mA
Peak Forward Current [2]	IFM	300	mA
Reverse Voltage	VR	5	V
Thermal Resistance [1] (Junction/ambient)	Rth j-a	180	°C/W
Thermal Resistance [1] (Junction/solder point)	Rth j-S	85	°C/W
Electrostatic Discharge Threshold (HBM)		8000	V

Notes:

Electrical / Optical Characteristics at Ta=25°C

Parameter	Symbol	Value	Unit	
Forward Voltage IF = 150mA [Min.]		2.7	V	
Forward Voltage IF = 150mA [Typ.]	VF [1]	3.5		
Forward Voltage IF = 150mA [Max.]		4.0		
Allowable Reverse Current [Max.]	lR	85	mA	
Temperature coefficient of VF IF=150mA, -10 ° C≤ T≤100 ° C [Typ.]	TCv	-3.1	mV/° C	
Temperature coefficient of X IF=150mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C [Typ.]	TCx	-0.15	10 ⁻³ /° C	
Temperature coefficient of Y IF=150mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C [Typ.]	TCy	-0.22	10 ⁻³ /° C	

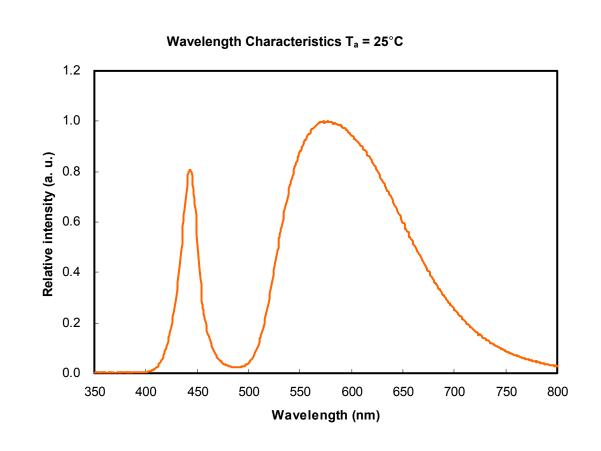
Note:

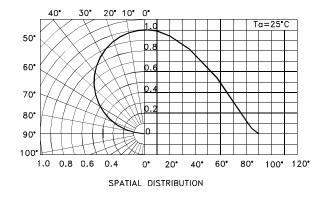
1.Forward Voltage: +/-0.1V.

SPEC NO: DSAM3339 **REV NO: V.3B DATE: FEB/02/2013** PAGE: 3 OF 8 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Y.Liu ERP: 1201008033

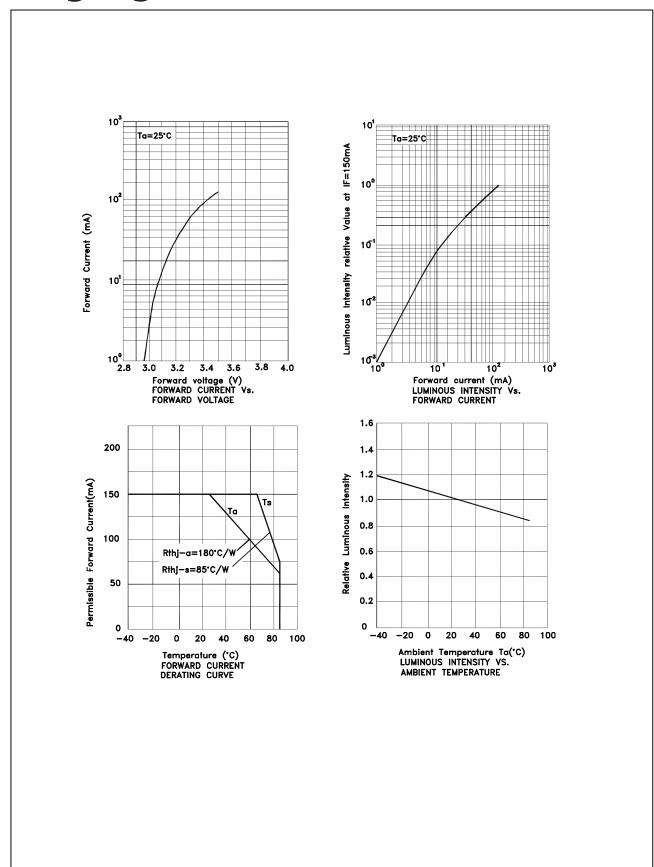
^{1.} Results from mounting on PC board FR4(pad size \geq 70mm²), mounted on pc board-metal core PCB is recommend for lowest thermal Resistance.

^{2.1/10} Duty Cycle, 0.1ms Pulse Width.



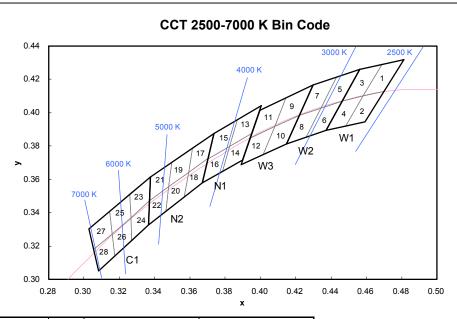


SPEC NO: DSAM3339 APPROVED: WYNEC REV NO: V.3B CHECKED: Allen Liu DATE: FEB/02/2013 DRAWN: Y.Liu PAGE: 4 OF 8 ERP: 1201008033



SPEC NO: DSAM3339 REV NO: V.3B
APPROVED: WYNEC CHECKED: Allen Liu

DATE: FEB/02/2013 DRAWN: Y.Liu PAGE: 5 OF 8 ERP: 1201008033



Color	Group	Chromaticity Regions	CCT (K)			
Coloi	Group	Chilomaticity Regions	Min.	Тур.	Max.	
	W1	1, 2, 3, 4	2580	2700	2870	
Warm White	W2	5, 6, 7, 8	2870	3000	3220	
	W3	9, 10, 11, 12	3220	3500	3710	
Neutral White	N1	13, 14, 15, 16	3710	4000	4260	
Neutral Write	N2	17, 18, 19, 20, 21, 22	4260	4700	5310	
Cool White	C1	23, 24, 25, 26, 27, 28	5310	6000	7040	

Notes:

Shipment may contain more than one chromaticity regions. Orders for single chromaticity region are generally not accepted.

Measurement tolerance of the chromaticity coordinates is ± 0.01 .

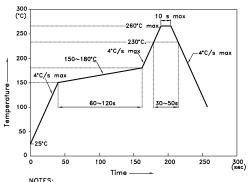
Coc	Cool White C1 23, 24,		4, 25,	26, 27, 28	5310	6000	7040	coordinates is ±	.0.01.		
	Х	у		Х	у		х	у		Х	у
	0.4582 0.4099	0.4147	0.3814		0.3702	0.3722		0.3481	0.3557		
1	0.4687	0.4289	8	0.4221	0.3984	15	0.3736	0.3874	22	0.3370	0.3472
	0.4813	0.4319	0	0.4342	0.4028	13	0.3869	0.3958		0.3364	0.3328
	0.4700	0.4126		0.4259	0.3853		0.3825	0.3798		0.3466	0.3411
	0.4483	0.3919	9	0.4080	0.3916		0.3670	0.3578	23	0.3376	0.3616
2	0.4582	0.4099		0.4146	0.4089	16	0.3702	0.3722		0.3260	0.3512
_	0.4700	0.4126		0.4299	0.4165		0.3825	0.3798		0.3265	0.3371
	0.4593	0.3944		0.4221	0.3984		0.3783	0.3646		0.3370	0.3472
	0.4465	0.4071		0.4017	0.3751		0.3736	0.3874	24	0.3370	0.3472
3	0.4562	0.4260	10	0.4080	0.3916	17	0.3616	0.3788		0.3265	0.3371
	0.4687	.4687 0.4289		0.4221	0.3984		0.3592	0.3641		0.3270	0.3230
	0.4582	0.4099	0.4147	0.4147	0.3814		0.3703	0.3726		0.3364	0.3328
	0.4373	0.3893	0.3941 0.3996 0.4146 0.4080	0.3941	0.3848		0.3703	0.3726	25	0.3260	0.3512
4	0.4465	0.4071		0.3996	0.4015	18	0.3592	0.3641		0.3144	0.3408
-	0.4582	0.4099		0.4146	0.4089	10	0.3568	0.3495		0.3160	0.3274
	0.4483	0.3919		0.4080	0.3916		0.3670	0.3578		0.3265	0.3371
	0.4342	0.4028		0.3889	0.3690		0.3616	0.3788		0.3265	0.3371
5	0.4430	0.4212	12	0.3941	0.3848	19	0.3496	0.3702	26	0.3160	0.3274
5	0.4562	0.4260	12	0.4080	0.3916	19	0.3481	0.3557		0.3175	0.3139
	0.4465	0.4071		0.4017	0.3751		0.3592	0.3641		0.3270	0.3230
	0.4259	0.3853		0.3825	0.3798		0.3592	0.3641		0.3144	0.3408
	0.4342	0.4028	13	0.3869	0.3958	20	0.3481	0.3557	27	0.3028	0.3304
6	0.4465	0.4071		0.4006	0.4044	20	0.3466	0.3411		0.3055	0.3177
	0.4373	0.3893		0.3950	0.3875		0.3568	0.3495		0.3160	0.3274
	0.4221	0.3984	14	0.3783	0.3646		0.3496	0.3702	28	0.3160	0.3274
	0.4299	0.4165		0.3825	0.3798	21	0.3376	0.3616		0.3055	0.3177
7	0.4430	0.4212		0.3950	0.3875		0.3370	0.3472		0.3081	0.3049
	0.4342	0.4028		0.3898	0.3716		0.3481	0.3557		0.3175	0.3139

SPEC NO: DSAM3339 APPROVED: WYNEC REV NO: V.3B CHECKED: Allen Liu DATE: FEB/02/2013 DRAWN: Y.Liu PAGE: 6 OF 8 ERP: 1201008033

AA3535QR4A25Z4S-W2

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

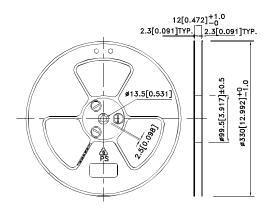
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

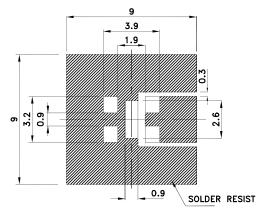
1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 3.Number of reflow process shall be 2 times or less.

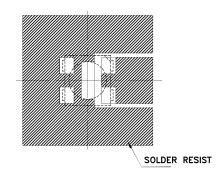
Reel Dimension



Recommended Soldering Pattern

(Units: mm; Tolerance: ±0.1)





Tape Specifications (Units: mm)

TAPE $\emptyset 1.50^{+0.1}_{-0}$ 2±0.1 4±0.05 0.25±0.05 1,2 \oplus 1.42±0.1 12±0.2 1 | 2 <u>ເດ {</u> 3,4 Slug 8±0.1

SPEC NO: DSAM3339 APPROVED: WYNEC

REV NO: V.3B CHECKED: Allen Liu

3.7±0.1

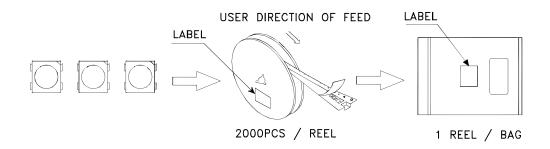
A-A SECTION

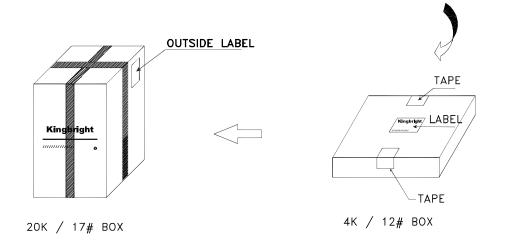
DATE: FEB/02/2013 DRAWN: Y.Liu

PAGE: 7 OF 8 ERP: 1201008033

PACKING & LABEL SPECIFICATIONS

AA3535QR4A25Z4S-W2







SPEC NO: DSAM3339 APPROVED: WYNEC REV NO: V.3B CHECKED: Allen Liu DATE: FEB/02/2013 DRAWN: Y.Liu PAGE: 8 OF 8 ERP: 1201008033